

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
- Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

Octal Buffer/Line Driver with 3-State Outputs

The SN74LS240 and SN74LS244 are Octal Buffers and Line Drivers designed to be employed as memory address drivers, clock drivers and bus-oriented transmitters/receivers which provide improved PC board density.

- Hysteresis at Inputs to Improve Noise Margins
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Input Clamp Diodes Limit High-Speed Termination Effects

GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage	4.75	5.0	5.25	V
T _A	Operating Ambient Temperature Range	0	25	70	°C
I _{OH}	Output Current - High			-3.0	mA
				-15	mA
I _{OL}	Output Current - Low			24	mA



ON Semiconductor

http://onsemi.com

LOW POWER SCHOTTKY

MARKING DIAGRAMS



SN74LS24xN SWYYWW AWLYYWW

PDIP-20 N SUFFIX CASE 738



LS24x AWLYYWW O

SOIC-20 DW SUFFIX CASE 751D



1

74LS24x AWLYWW UUUUUUUUUU

x = 0 or 4

A = Assembly Location

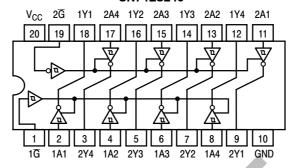
WL = Wafer Lot YY = Year WW = Work Week

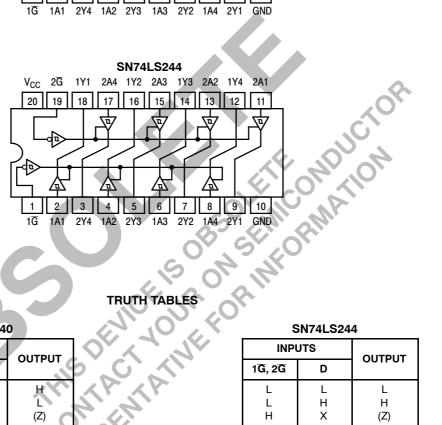
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

LOGIC AND CONNECTION DIAGRAMS DIP (TOP VIEW)

SN74LS240





SN74LS240

INP	OUTPUT	
1 G , 2 G	D	OUIPUI
IFF	L H X	H L (Z)

H = HIGH Voltage Level L = LOW Voltage Level X = Immaterial Z = HIGH Impedance

INPL	OUTPUT	
1 G , 2 G	001701	
L	L	L
L	Н	Н
Н	X	(Z)

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

			Limits			
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V _{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs
V _{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs
$V_{T+}-V_{T-}$	Hysteresis	0.2	0.4		V	V _{CC} = MIN
V _{IK}	Input Clamp Diode Voltage		-0.65	-1.5	V	V _{CC} = MIN, I _{IN} = –18 mA
V _{OH}	Output HIGH Voltage	2.4	3.4		V	V_{CC} = MIN, I_{OH} = -3.0 mA
VOH	Output HIGH Voltage	2.0			V	V _{CC} = MIN, I _{OH} = MAX
.,	O to 11 OWY the co		0.25	0.4	V	$I_{OL} = 12 \text{ mA}$ $V_{CC} = V_{CC} \text{ MIN},$
V_{OL}	Output LOW Voltage		0.35	0.5	V	V _{IN} = V _{IL} or V _{IH} per Truth Table
I _{OZH}	Output Off Current HIGH			20	μΑ	V _{CC} = MAX, V _{OUT} = 2.7 V
I _{OZL}	Output Off Current LOW			-20	μА	V _{CC} = MAX, V _{OUT} = 0.4 V
Luc	Input HIGH Current			20	μΑ	$V_{CC} = MAX, V_{IN} = 2.7 V$
I _{IH}	input man ounent			0.1	mA	$V_{CC} = MAX, V_{IN} = 7.0 V$
I _{IL}	Input LOW Current			-0.2	mA	$V_{CC} = MAX$, $V_{IN} = 0.4 V$
I _{OS}	Output Short Circuit Current (Note 1)	-40		-225	mA	V _{CC} = MAX
	Power Supply Current Total, Output HIGH			27	0	AIC MA
	Total, Output LOW LS240			44	C	
I _{CC}	LS244		C	46	mA	V _{CC} = MAX
	Total at HIGH Z			50	1	
	LS244			54	S.	

^{1.} Not more than one output should be shorted at a time, nor for more than 1 second.

AC CHARACTERISTICS (T_A = 25°C, V_{CC} = 5.0 V)

	.5	Y (Limits			
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
t _{PLH} t _{PHL}	Propagation Delay, Data to Output LS240		9.0 12	14 18	ns	
t _{PLH} t _{PHL}	Propagation Delay, Data to Output LS244	5	12 12	18 18	ns	C_L = 45 pF, R_L = 667 Ω
t _{PZH}	Output Enable Time to HIGH Level		15	23	ns	
t _{PZL}	Output Enable Time to LOW Level		20	30	ns	
t _{PLZ}	Output Disable Time from LOW Level		15	25	ns	C _L = 5.0 pF,
t _{PHZ}	Output Disable Time from HIGH Level		10	18	ns	$R_L = 667 \Omega$

AC WAVEFORMS

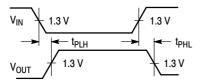


Figure 1.

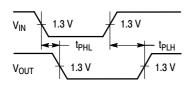


Figure 2.

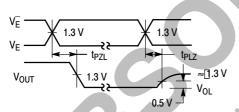


Figure 3.

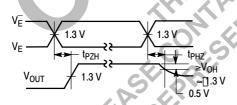
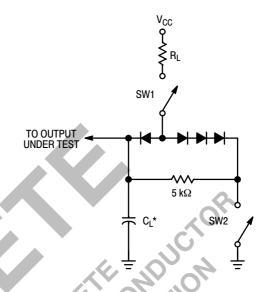


Figure 4.



SWITCH POSITIONS

SYMBOL	SW1	SW2
t _{PZH}	Open	Closed
t _{PZL}	Closed	Open
t _{PLZ}	Closed	Closed
t _{PHZ}	Closed	Closed

Figure 5.

DEVICE ORDERING INFORMATION

Device Order Number	Package Type	Tape and Reel Size	
SN74LS240N	PDIP-20	1440 Units/Box	
SN74LS240DW	SOIC-WIDE	38 Units/Rail	
SN74LS240DWR2	SOIC-WIDE	2500/Tape and Reel	
SN74LS240M	SOEIAJ-20	See Note 2	
SN74LS240MEL	SOEIAJ-20	See Note 2	
SN74LS244N	PDIP-20	1440 Units/Box	
SN74LS244DW	SOIC-WIDE	38 Units/Rail	
SN74LS244DWR2	SOIC-WIDE	2500/Tape and Reel	
SN74LS244M	SOEIAJ-20	See Note 2	
SN74LS244MEL	SOEIAJ-20	See Note 2	

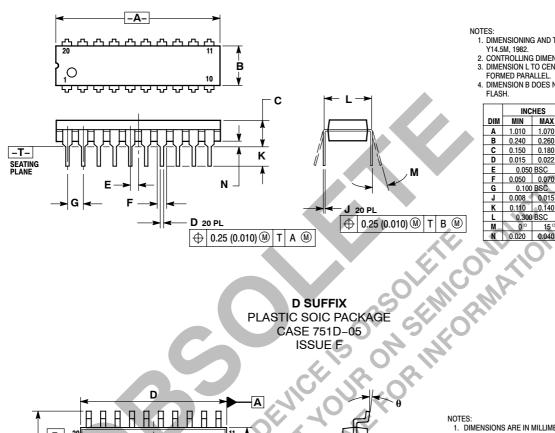
^{2.} For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.



PACKAGE DIMENSIONS

N SUFFIX PLASTIC PACKAGE

CASE 738-03 **ISSUE E**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.

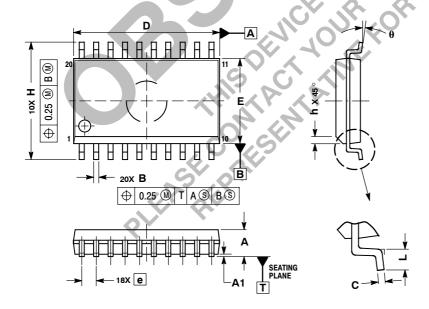
 CONTROLLING DIMENSION: INCH.

 DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.

 DIMENSION B DOES NOT INCLUDE MOLD

	INCHES		MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	1.010	1.070	25.66	27.17
В	0.240	0.260	6.10	6.60
С	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
Е	0.050	BSC <	1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100	BSC	2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62	BSC
M	°	1 <u>5</u> °	0°	15°
N	0.020	0.040	0.51	1.01

D SUFFIX PLASTIC SOIC PACKAGE CASE 751D-05 ISSUE F



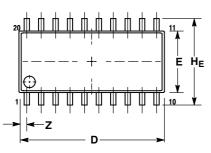
- DIMENSIONS ARE IN MILLIMETERS.
 INTERPRET DIMENSIONS AND TOLERANCES
- PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

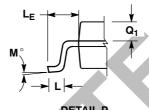
	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
С	0.23	0.32		
D	12.65	12.95		
Е	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
A	0 0	7 0		

PACKAGE DIMENSIONS

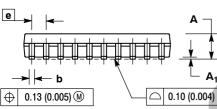
M SUFFIX

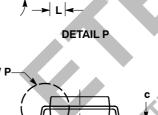
SOEIAJ PACKAGE CASE 967-01 **ISSUE 0**











NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 THE LEAD WIDTH DIMENSION (b) DOES NOT
- INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1	2.05		0.081	
A ₁	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
C	0.18	0.27	0.007	0.011	
D	12.35	12.80	0.486	0.504	
E	5.10	5.45	0.201	0.215	
e 👝	1.27	BSC	0.050 BSC		
HE	7.40	8.20	0.291	0.323	
	0.50	0.85	0.020	0.033	
LΕ	1.10	1.50	0.043	0.059	
M	0 °	10 °	0 °	10°	
Q_1	0.70	0.90	0.028	0.035	
Z		0.81		0.032	

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